

Title (en)

PROCESS FOR THE ELECTROLESS DEPOSITING OF NOBLE METAL LAYERS ON THE SURFACES OF NON-NOBLE METALS

Publication

EP 0081183 B1 19870513 (DE)

Application

EP 82111045 A 19821130

Priority

DE 3148330 A 19811207

Abstract (en)

1. Claims for the contracting states : BE, CH, DE, FR, GB, IT, LI, LU, NL, SE Process for the currentless deposition of silver or gold layers on the appropriate less electro-positive metals by contacting the object to be coated with a coating bath which contains a metal complex which is obtainable by reaction of a chloride of monovalent silver or gold with a base, which is capable of complex formation with the silver or gold, and with hydrochloric acid. 1. Claims for the contracting state : Austria Process for the currentless deposition of silver or gold layers on to appropriate less electro-positive metals by contacting the object to be coated with a coating bath which contains a metal complex which is obtainable by reaction of a chloride of monovalent silver or gold with a base, which is capable of complex formation with the silver or gold, and with hydrochloric acid.

IPC 1-7

C23C 18/54

IPC 8 full level

C23C 18/38 (2006.01); **C23C 18/40** (2006.01); **C23C 18/42** (2006.01); **C23C 18/44** (2006.01); **C23C 18/54** (2006.01)

CPC (source: EP US)

C23C 18/38 (2013.01 - EP US); **C23C 18/42** (2013.01 - EP US)

Citation (examination)

GB 1411971 A 19751029 - ICI LTD

Cited by

USRE45279E; US5955141A; CN1071805C; US6869637B2; WO9617974A1; USRE45175E; US6395329B2; US6860925B2; US9072203B2; US8349393B2; US8986434B2; US9730321B2

Designated contracting state (EPC)

AT BE CH DE FR GB IT LI LU NL SE

DOCDB simple family (publication)

EP 0081183 A1 19830615; **EP 0081183 B1 19870513**; AT E27187 T1 19870515; CA 1236843 A 19880517; DE 3148330 A1 19830609; DE 3276334 D1 19870619; JP H0230389 B2 19900705; JP S58104168 A 19830621; US 4908241 A 19900313

DOCDB simple family (application)

EP 82111045 A 19821130; AT 82111045 T 19821130; CA 417092 A 19821206; DE 3148330 A 19811207; DE 3276334 T 19821130; JP 21347182 A 19821207; US 22238688 A 19880721